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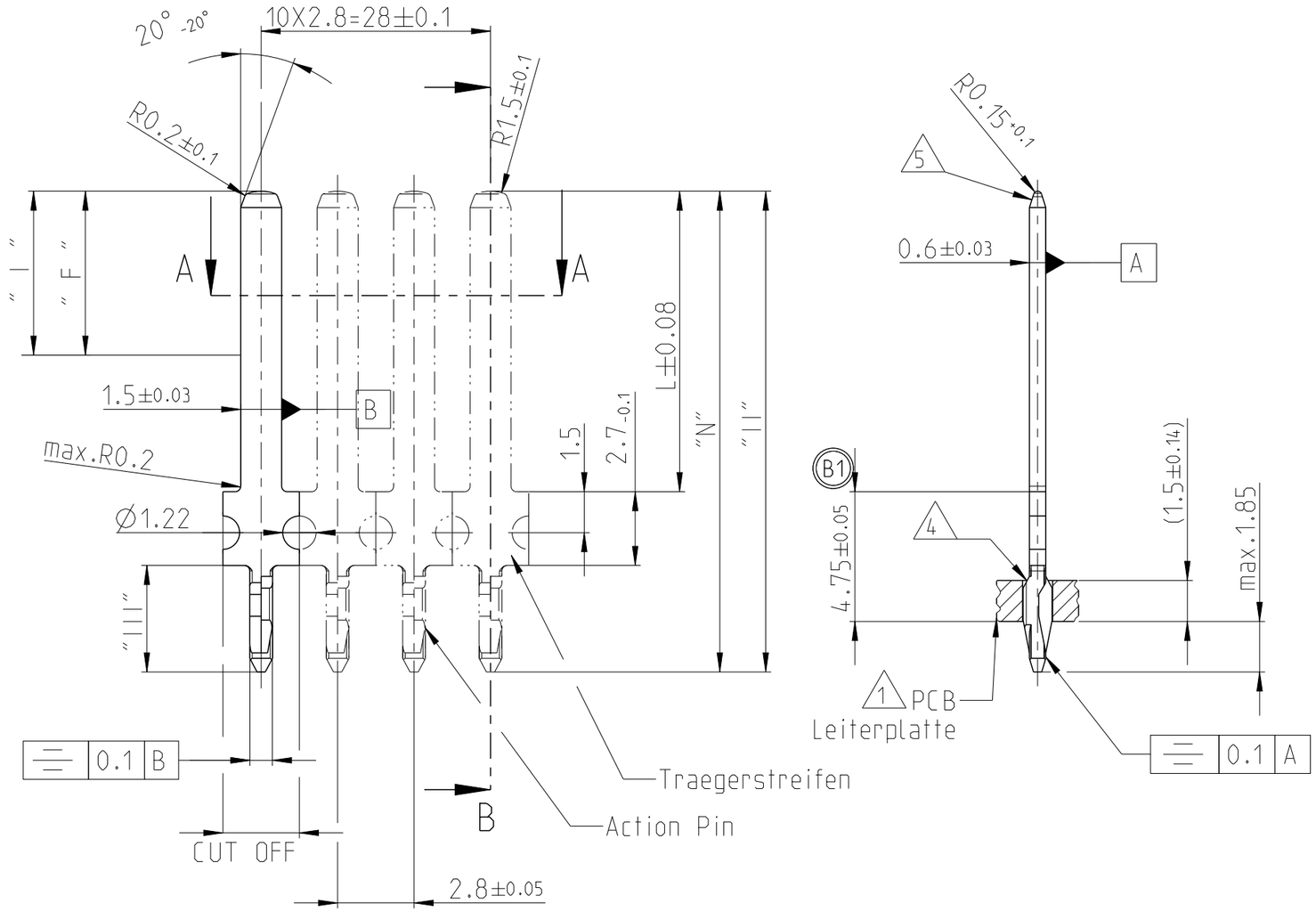
Prj. No: EGAUT00043

REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	B	NEW DRAWING	10JUN2015	KK	DD
	B1	DRW UPDATE, POSITION PCB CORRECTED	07DEC2015	ST	SR



Bemerkungen
NOTES

1. Verwendung fuer Leiterplattendicke 1.5 ±0.14mm(FR4)
USED ON PCB-THICKNESS...

2. Verarbeitungswerkzeug: X-Y-Einsetzmaschine .....
APPLICATION TOOL: X-Y-INSERTIONMACHINE ....

3. Loetbarkeit nach DIN 40 046
SOLDERABILITY ACCORDING TO ....

4. Einpresszone fuer 1.5 mm Leiterplatte
Anforderungen an Leiterplatten-Loch
PRESS-IN AREA FOR .... PCB
REQUIREMENTS ON PBC-HOLE

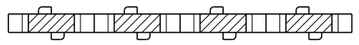
Platiertes Loch:
PLATED HOLE:...

- gebohrtes Loch: 1.15±0.025mm
DRILLED HOLE :
- Cu - Dicke : 25µm bis 75µm
...THICKNESS :
- Sn-Dicke : 4µm bis 15µm
...THICKNESS :
- Fertiges Loch : 0.94mm bis 1.09mm
FINISHED HOLE :

5. Kein Grat oder scharfe Kanten zulaessig
NO BURRS OR SHARP EDGES PERMITTED

6. Splice frei
SPLICE FREE

Massgebend ist der deutsche Text.
ONLY THE GERMAN LANGUAGE VERSION SHALL BE BINDING.



A-A

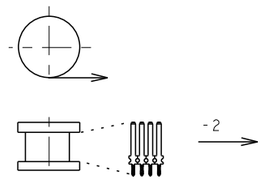
6

Zone "I" : Schichtdicke 1.0µm bis 3.0µm Sn
AREA "I" : COAT THICKNESS ....UNTIL...

Zone "II" : Schichtdicke 1.3µm bis 2.2µm Ni
AREA "II" : COAT THICKNESS ....UNTIL...

Zone "III": Schichtdicke 0.8µm bis 1.8µm Sn
AREA "III": COAT THICKNESS ....UNTIL...

DIRECTION OFF TOP OF REEL



PART NO Bestell-Nr.	REV	MATERIAL	SURFACE Oberflaeche		"F"	"L"	"N"
1394353-2	B	CuNiSi F59	Sn 6		8	10.3	16.9

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:
~~0 PLC~~ ±0.1
~~1 PLC~~ ±-
~~2 PLC~~ ±-
~~3 PLC~~ ±-
~~4 PLC~~ ±-
ANGLES ±1°

MATERIAL - -

FINISH - -

DWN K.Kappes 10JUN2015
CHK S.Reichel 10JUN2015
APVD D.Duenkel 10JUN2015
PRODUCT SPEC -
APPLICATION SPEC -
WEIGHT -

TE Connectivity

NAME
1.5x0.6 Tab, ACTION PIN FOR 1mm HOLE
1.5x0.6 Tab, ACTION PIN fuer 1mm Loch
FREE STANDING/freistehend

SIZE A3 | CAGE CODE - | DRAWING NO C-1394353 | RESTRICTED TO -

Customer Drawing | SCALE 5:1 | SHEET 1 OF 1 | REV B1

1470-19 (3/13)